

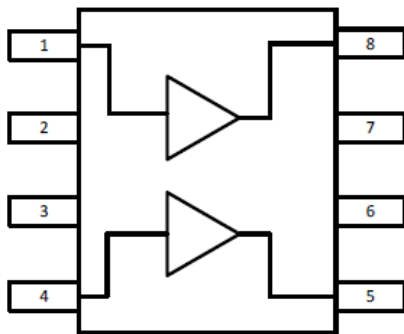
### Product Overview

The QPB8896 is a GaAs pHEMT RF balanced amplifier IC operating as return path amplifier capable of supporting FDX and DOCSIS 3.1 applications. This IC is designed to provide a low noise, high gain option for 5–700 MHz interface using a 5 V power supply to provide lower overall power dissipation. QPB8896 is in a convenient SOIC-8 package.



SOIC-8 with Exposed Pad

### Functional Block Diagram



Functional Block Diagram

Top View

### Key Features

- 5 MHz to 700 MHz Operation
- 5 V Operation
- High Gain: 25 dB Typical
- Low Noise Figure: 1.8 dB
- SOIC-8 Exposed Pad

### Applications

- Head End CMTS Equipment
- Post Amp for Return Path Optical Receivers
- Full Duplex Upstream
- DOCSIS 3.1 Optical Nodes

### Ordering Information

Part Number	Description
QPB8896SR	7" Reel with 100 pieces
QPB8896TR13	13" Reel with 2500 pieces
QPB8896PCK	5–700 MHz PCBA with 5 pc sample bag
QPB8896PCK-1	5–300 MHz PCBA with 5 pc sample bag



# QPB8896

## 25 dB Balanced Return Path Amplifier (5 – 700 MHz)

### Absolute Maximum Ratings

Parameter	Rating
Supply Voltage ( $V_{DD}$ )	+8 V
Supply Current ( $I_{DD}$ )	360 mA
Maximum CW Input Power for $V_{DD} = 5$ V	+1 dBm
Operating Temperature Range	-40 to +85 °C
Storage Temperature Range	-40 to +150 °C
Maximum Junction Temperature	+160 °C

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

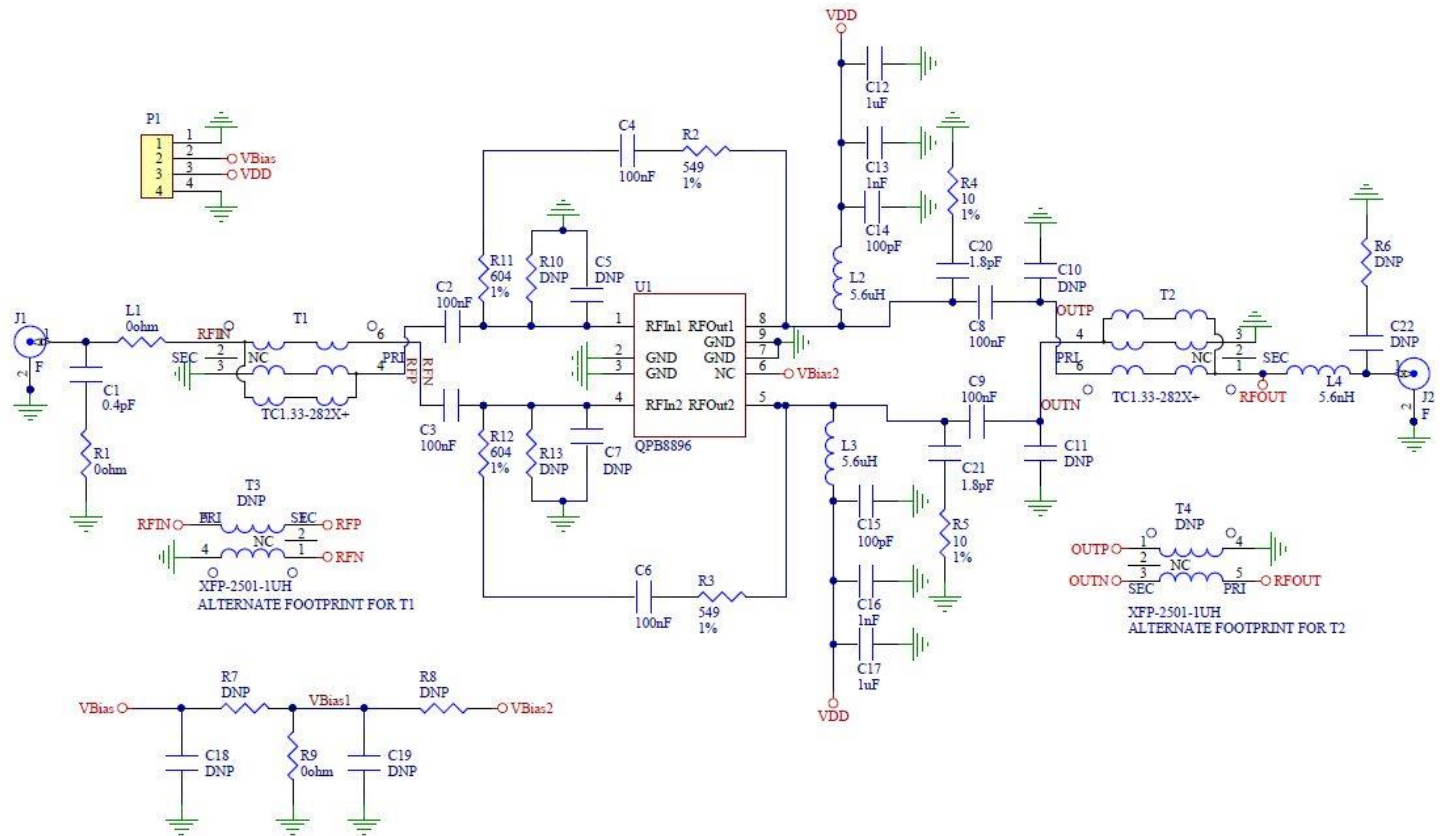
### Electrical Specifications

Parameter	Condition <sup>(1)</sup>	Min	Typ	Max	Unit
Supply Voltage ( $V_{DD}$ )			5		V
Supply Current ( $I_{DD}$ )			275		mA
Frequency Range		5		700	MHz
Gain	Full Bandwidth		25.0		dB
Gain Flatness	Max. deviation from line using least squares fit from 5 to 700 MHz		±0.5		dB
Gain Tilt	Gain (700 MHz) – Gain (5 MHz)		-0.1		dB
Input Return Loss	5 MHz		33		dB
	125 MHz		26		dB
	300 MHz		20		dB
	700 MHz		16		dB
Output Return Loss	5 MHz		20		dB
	125 MHz		22		dB
	300 MHz		18		dB
	700 MHz		16.5		dB
Reverse Isolation			30		dB
Noise Figure	(includes balun loss)		1.8		dB
ACLR	$P_{out} = 62$ dBmV, 5 – 195 MHz OFDM w/ 9.6 MHz exclusion band.		59.7		dB
DTO/DSO	$f_1=13$ MHz, $f_2=19$ MHz 58.75 dBmV/tone		-60		dBc
OIP2	5 – 700 MHz 2-Tone, 6 MHz spacing 3 dBm/tone		70		dBm
OIP3	5 – 700 MHz 2-Tone, 6 MHz spacing 5 dBm/tone		38		dBm
Output P1dB	Full Band		22.6		dBm
Thermal Resistance	$\Theta_{JC}$		23		°C/W

#### Notes:

1. Typical performance at these conditions: Temp = +25 °C,  $V_{DD} = +5$  V, 75  $\Omega$  system

**Evaluation Board Schematic for QPB8896-4000 (5 – 700 MHz)**





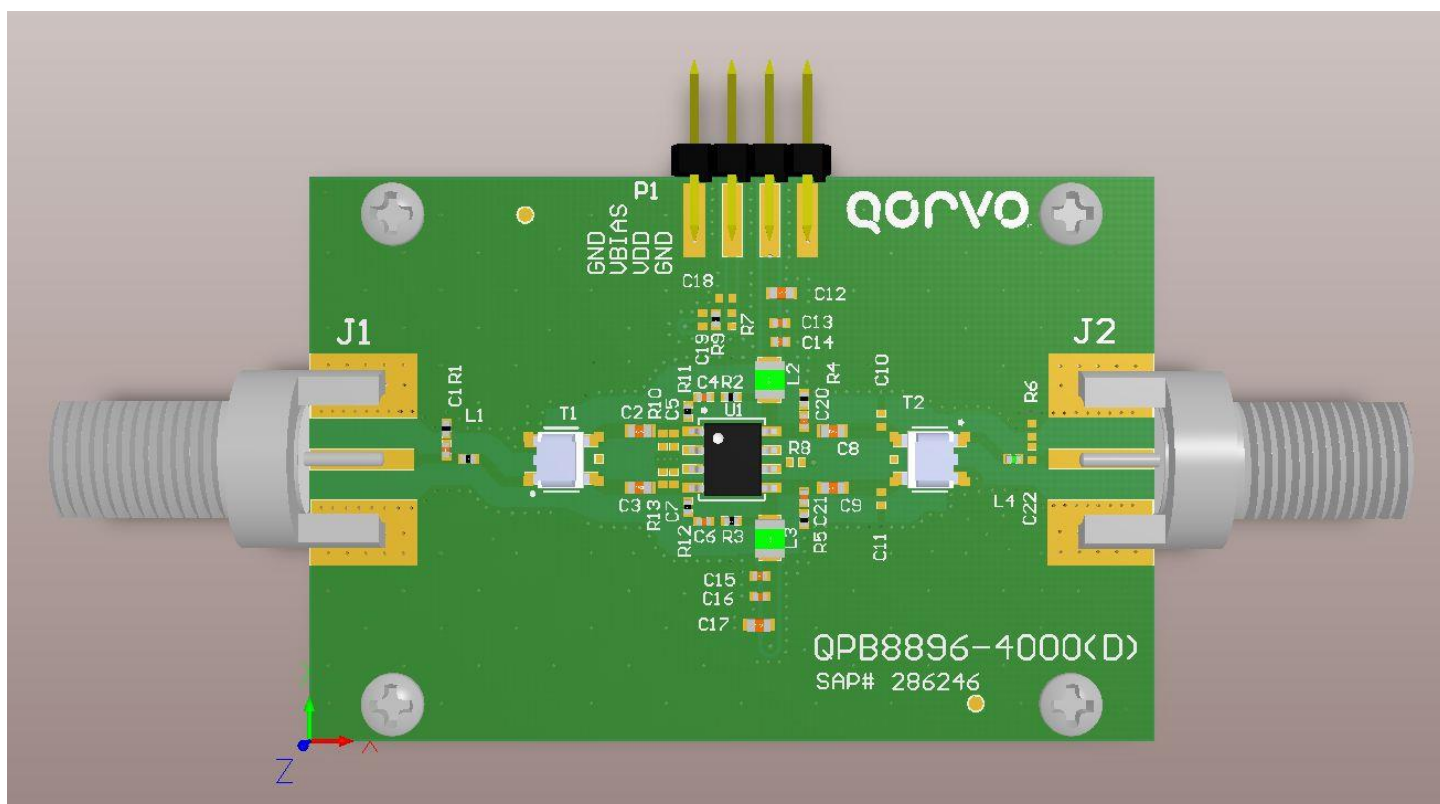
# QPB8896

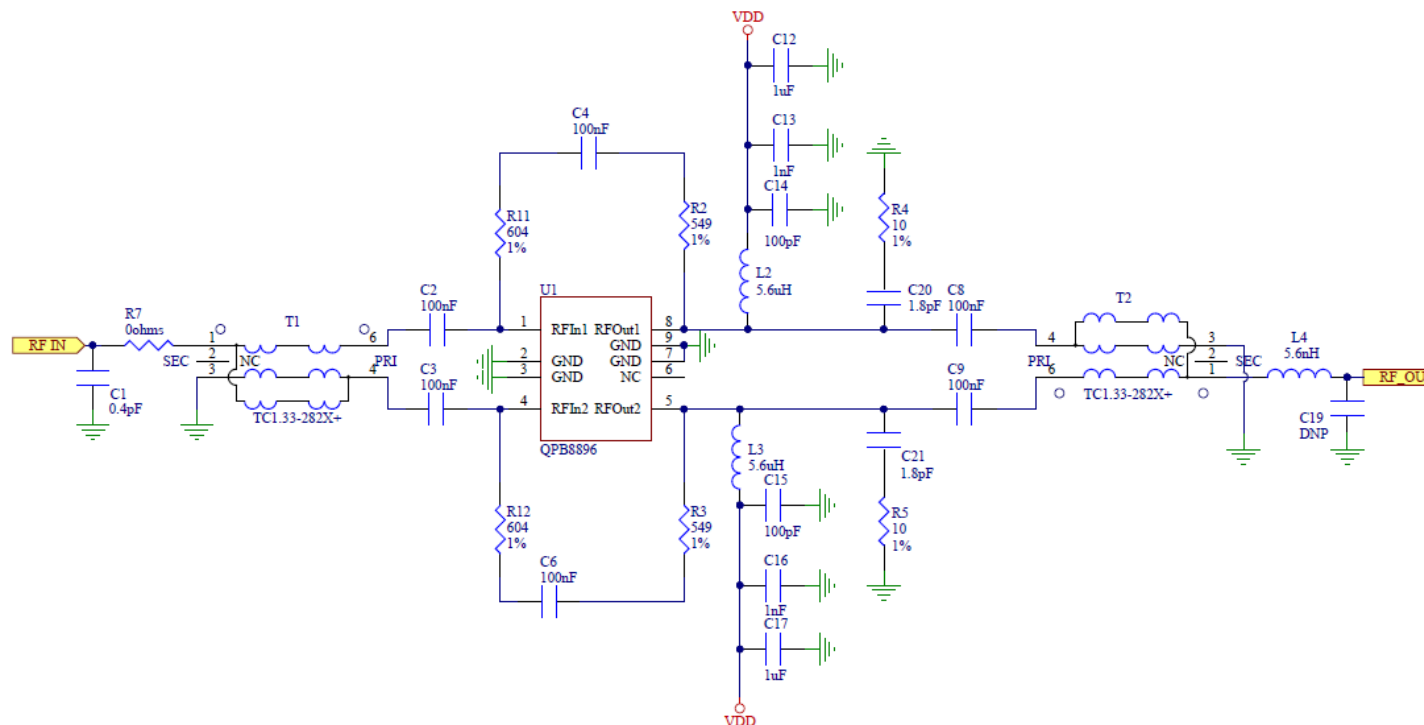
## 25 dB Balanced Return Path Amplifier (5 – 700 MHz)

### Evaluation Board Bill of Materials for QPB8896-4000 (5 – 700 MHz)

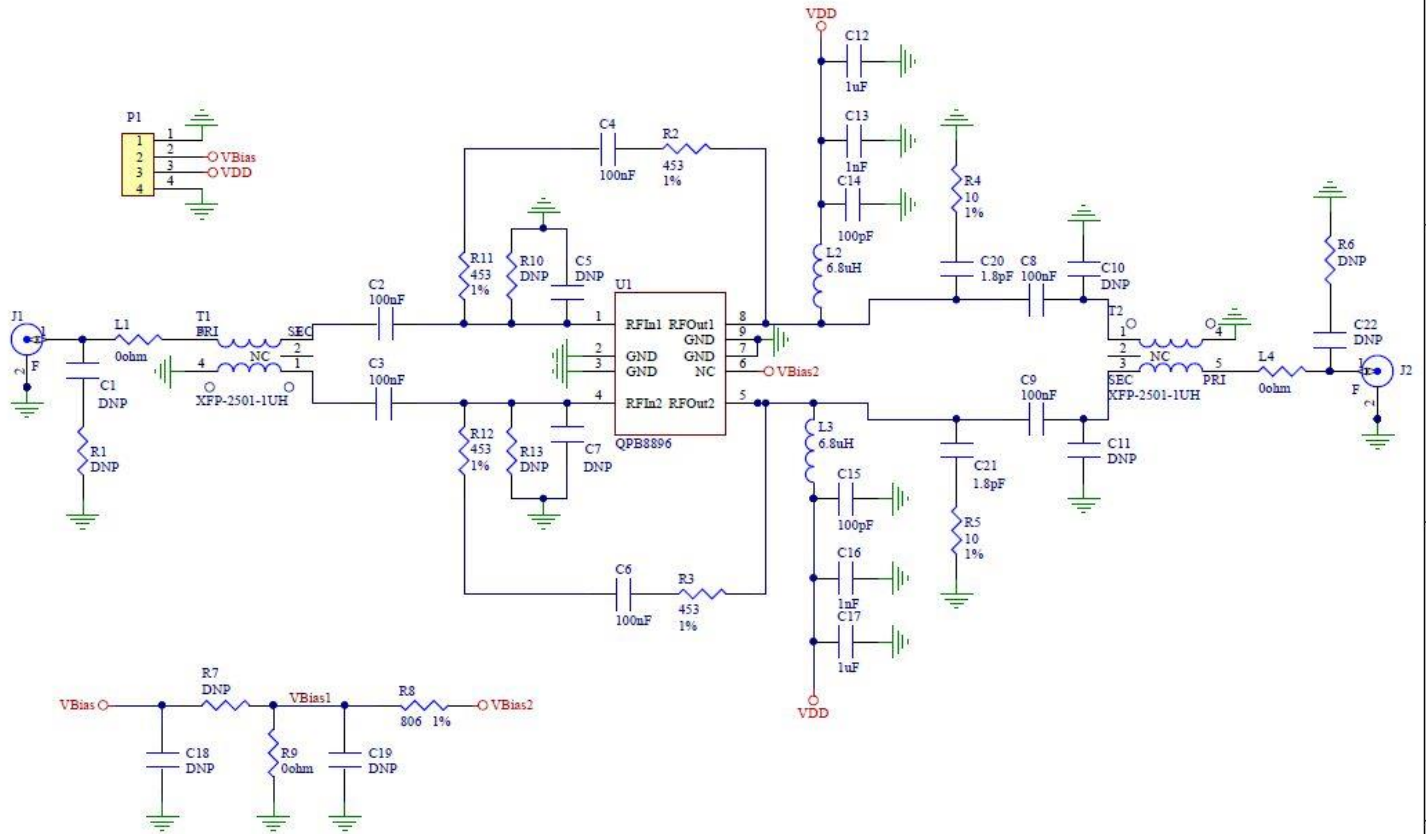
Reference Designator	Description	Manufacturer	Part Number
PCB	QPB8896-4000	Viasystems	QPB8896-4000
U1	Balanced Return Path Amplifier, 5-700 MHz	Qorvo	QPB8896SB
C1	CAP, 0.4 pF, +/-0.05 pF, 50 V, C0G, 0402	Murata Electronics	GRM1555C1HR40WA01D
C13, C16	CAP, 1000 pF, 10 %, 50 V, X7R, 0402	Taiyo Yuden	RM UMK105BJ102KV-F
C4, C6	CAP, 0.1 uF, 10 %, 16 V, X7R, 0402	Murata Electronics	GRM155R71C104KA88D
C2, C3, C8, C9	CAP, 0.1 uF, 10 %, 16 V, X7R, 0603	Murata Electronics	GRM188R71C104KA01D
C20, C21	CAP, 1.8 pF, +/-0.1 pF, 50 V, C0G, 0402	Murata Electronics	GRM1555C1H1R8BA01E
C12, C17	CAP, 1 uF, 10 %, 16 V, X7R, 0603	Murata Electronics	GRM188R71C105KA12D
C14, C15	CAP, 100 pF, 5 %, 50 V, C0G, 0402	Taiyo Yuden	RM UMK105CG101JV-F
L2, L3	IND, 5.6 uH, 5 %, W/W, 1008	Coilcraft, Inc.	1008LS-562XJLC
R2, R3	RES, 549 $\Omega$ , 1 %, 1/10 W, 0402	Kamaya, Inc	RMC1/16SK5490FTH
R11, R12	RES, 604 $\Omega$ , 1 %, 1/10 W, 0402	Kamaya, Inc	RMC1/16SK6040FTH
R4, R5	RES, 10 $\Omega$ , 1 %, 1/16 W, 0402	Panasonic Industrial Devices	ERJ-2RKF10R0X
R1, R9, L1	RES, 0 $\Omega$ , 0402	Kamaya, Inc	RMC1/16SJPTH
L4	IND, 5.6 nH, +/-0.1 nH, T/F, 0402	Murata Electronics	LQP15MN5N6B02D
T1, T2	XFMR, 5-2800 MHz, 100-75 $\Omega$	MiniCircuits	TC1.33-282X+
P1	CONN, HDR, ST, FRCTN LOCK, 4-PIN	Molex	22-23-2041
J1, J2	CONN, F FEM EDGE MOUNT, 75 $\Omega$ , 0.068"	Millimeter Wave, LLC	MW-846-C-DD-75
M1	HEATSINK BLOCK, 1.5 X 2.0 IN	Shenzhen Minxingda Automation	EEF-105441
S1-S4	SCREW, 2-56X3/16", SOCKET HEAD	McMaster-Carr Supply Co.	92196A076

Evaluation Board Assembly Drawing for QPB8896-4000 (5 – 700 MHz)





**Evaluation Board Schematic for QPB8896-4002 (5 – 300 MHz)**





# QPB8896

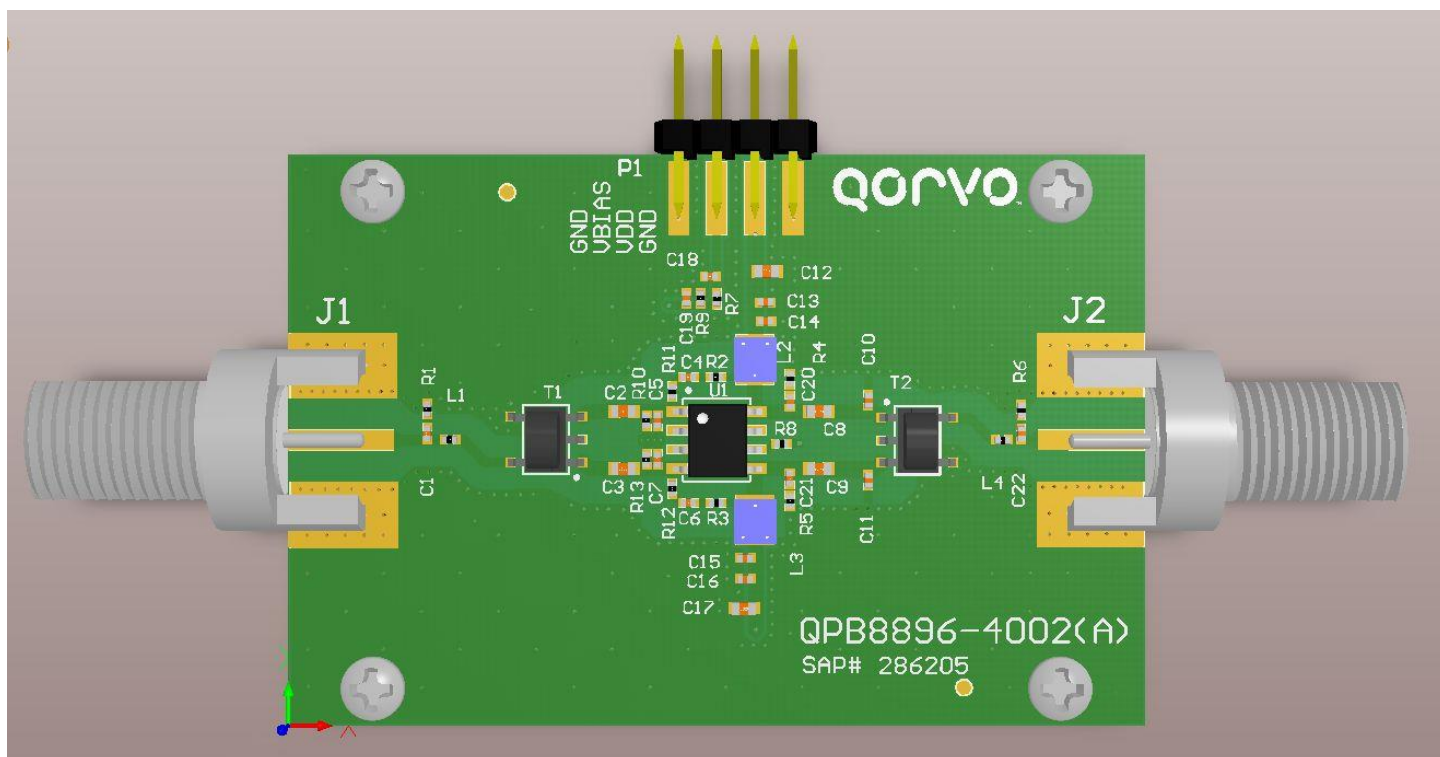
## 25 dB Balanced Return Path Amplifier (5 – 700 MHz)

### Evaluation Board Bill of Materials for QPB8896-4002 (5 – 300 MHz)

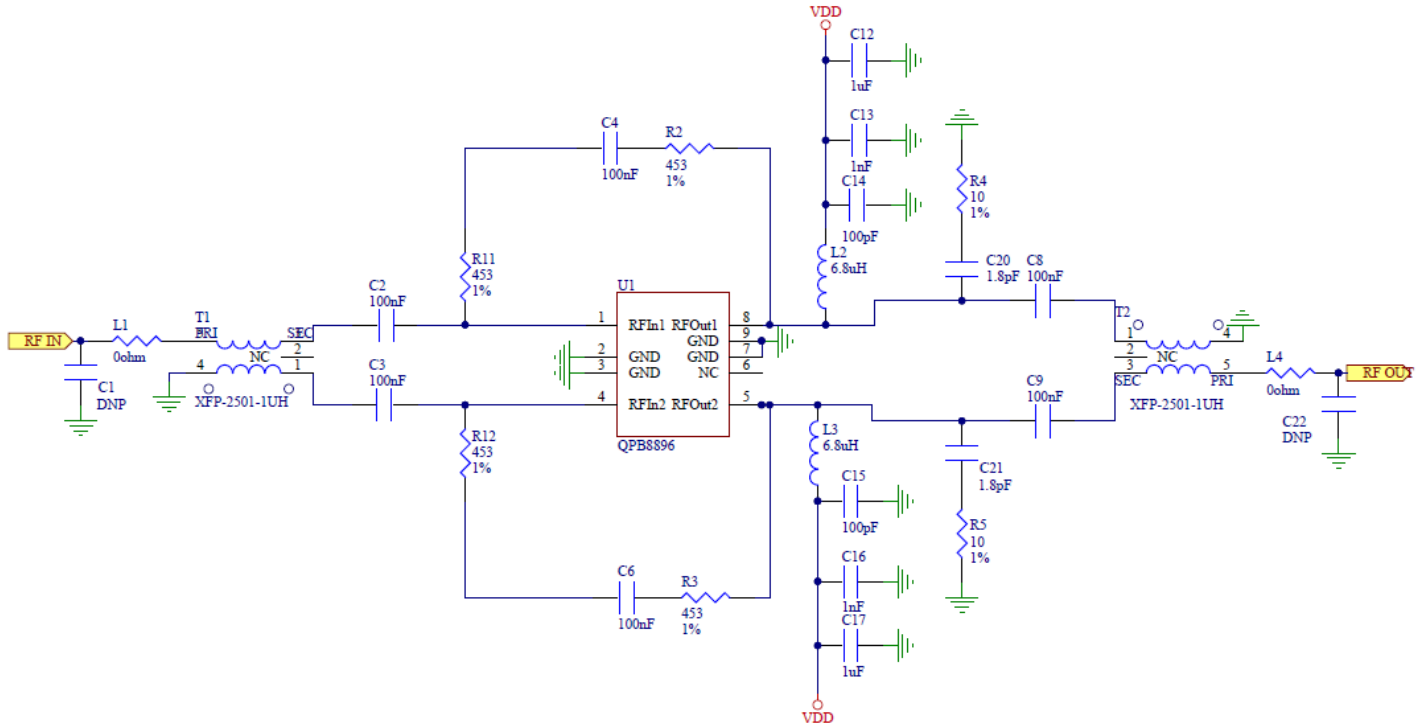
Reference Designator	Description	Manufacturer	Part Number
PCB	QPB8896-4002	Viasystems	QPB8896-4002
U1	Balanced Return Path Amplifier, 5-700 MHz	Qorvo	QPB8896SB
C13, C16	CAP, 1000 pF, 10 %, 50 V, X7R, 0402	Taiyo Yuden	RM UMK105BJ102KV-F
C4, C6	CAP, 0.1 uF, 10 %, 16 V, X7R, 0402	Murata Electronics	GRM155R71C104KA88D
C2, C3, C8, C9	CAP, 0.1 uF, 10 %, 16 V, X7R, 0603	Murata Electronics	GRM188R71C104KA01D
C20, C21	CAP, 1.8 pF, +/-0.1 pF, 50 V, C0G, 0402	Murata Electronics	GRM1555C1H1R8BA01E
C12, C17	CAP, 1 uF, 10 %, 16 V, X7R, 0603	Murata Electronics	GRM188R71C105KA12D
C14, C15	CAP, 100 pF, 5 %, 50 V, C0G, 0402	Taiyo Yuden	RM UMK105CG101JV-F
L2, L3	IND, 6.8 uH, 5 %, W/W, 1008	Coilcraft, Inc.	1008LS-682XJLC
R2, R3, R11, R12	RES, 453 $\Omega$ , 1 %, 1/10 W, 0402	Panasonic	ERJ-2RKF4530X
R4, R5	RES, 10 $\Omega$ , 1 %, 1/16 W, 0402	Panasonic Industrial Devices	ERJ-2RKF10R0X
R9, L1, L4	RES, 0 $\Omega$ , 0402	Kamaya, Inc	RMC1/16SJPTH
R8	RES, 806 $\Omega$ , 1 %, 1/10 W, 0402	Panasonic Industrial Devices	ERJ-2RKF8060X
T1, T2	BALUN, 1:1, 1-2500 MHz, 75 $\Omega$ , SMD	MiniRF	XFP-2501-1UH
P1	CONN, HDR, ST, FRCTN LOCK, 4-PIN	Molex	22-23-2041
J1, J2	CONN, F FEM EDGE MOUNT, 75 $\Omega$ , 0.068"	Millimeter Wave , LLC	MW-846-C-DD-75
M1	HEATSINK BLOCK, 1.5 X 2.0 IN	Shenzhen Minxingda Automation	EEF-105441
S1-S4	SCREW, 2-56 X 3/16", SOCKET HEAD	McMaster-Carr Supply Co.	92196A076
C1, C5, C7, C10, C11, C18, C19, C22, R1, R6, R7, R10, R13	DNP		



Evaluation Board Assembly Drawing for QPB8896-4002 (5 – 300 MHz)



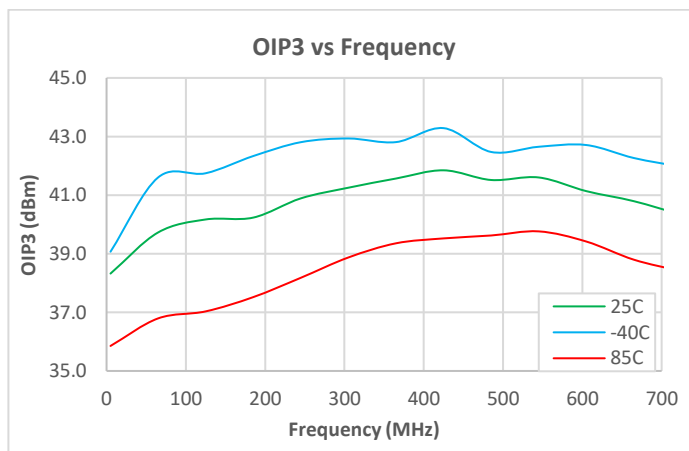
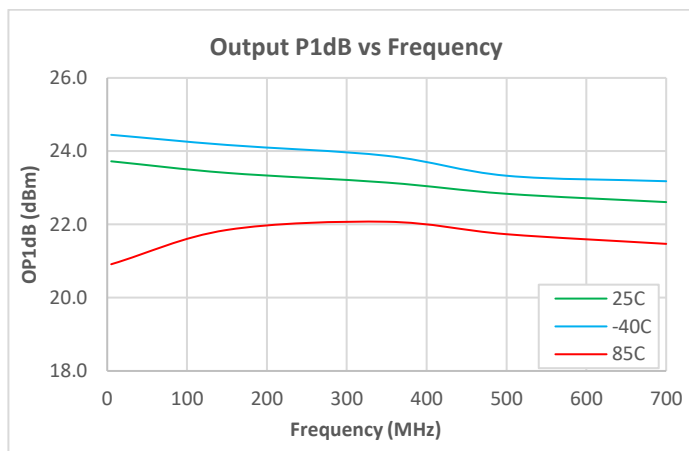
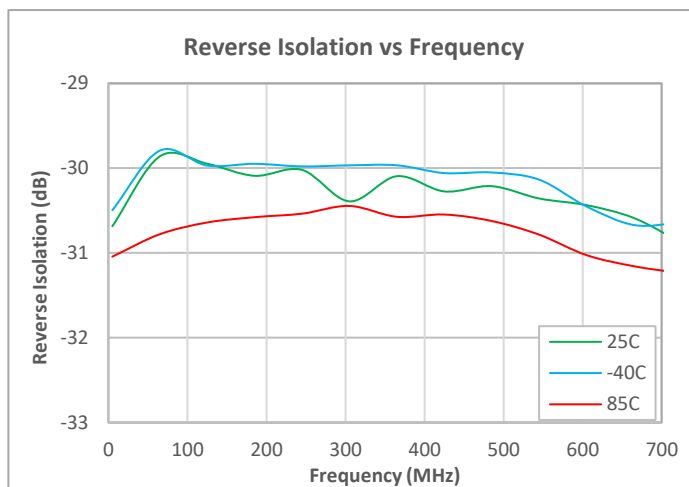
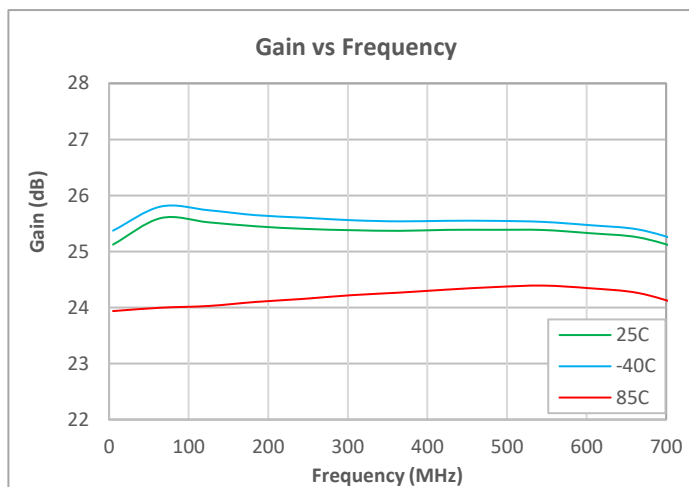
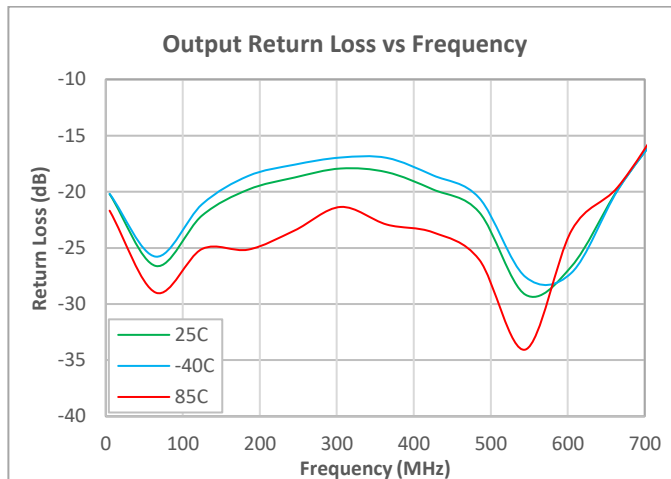
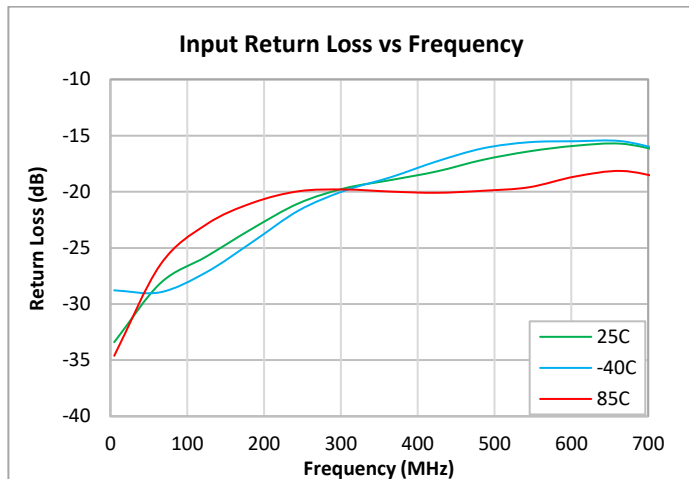
### Typical Applications Schematic (5 – 300 MHz)



#### Notes:

1. C1-L1 tune to optimize input return loss.
2. L4-C22 tune to optimize output return loss.
3. Feedback R11/R2/C4 and R12/R3/C6 can be adjusted to balance gain flatness versus return loss and IMD performance.
4. Lower insertion loss transformers help reduce noise figure  $\leq 1.1$  dB.

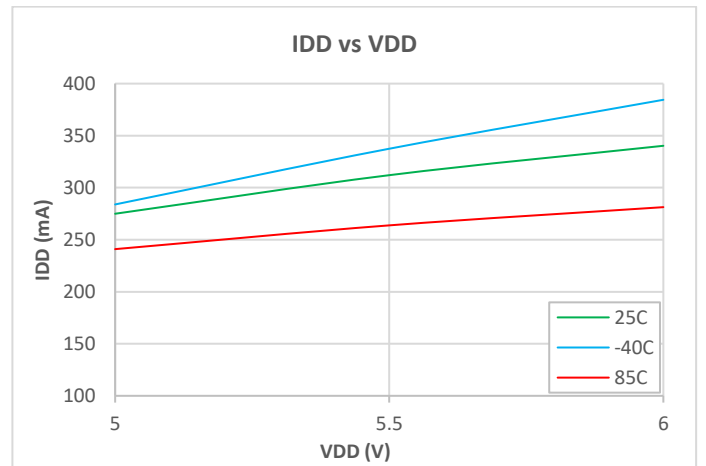
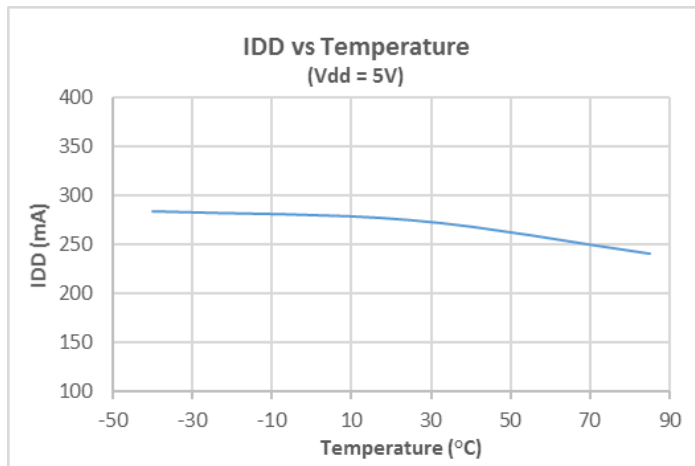
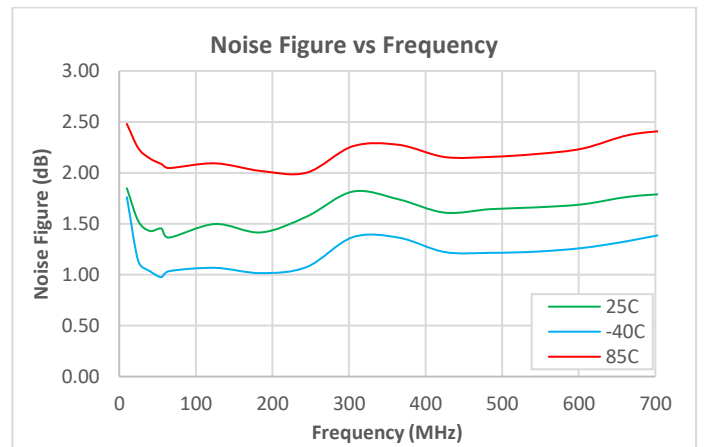
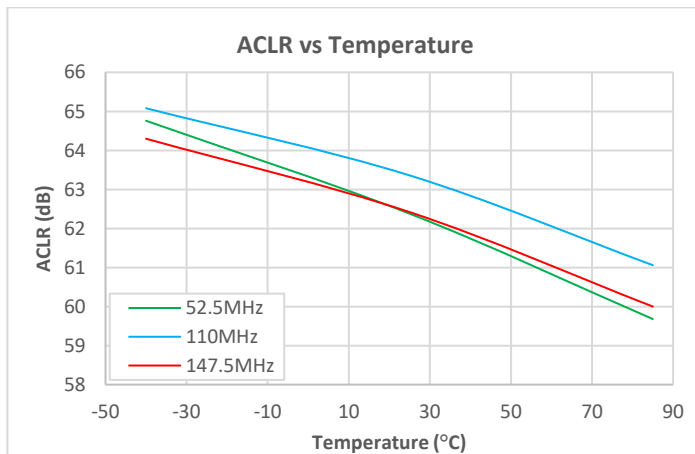
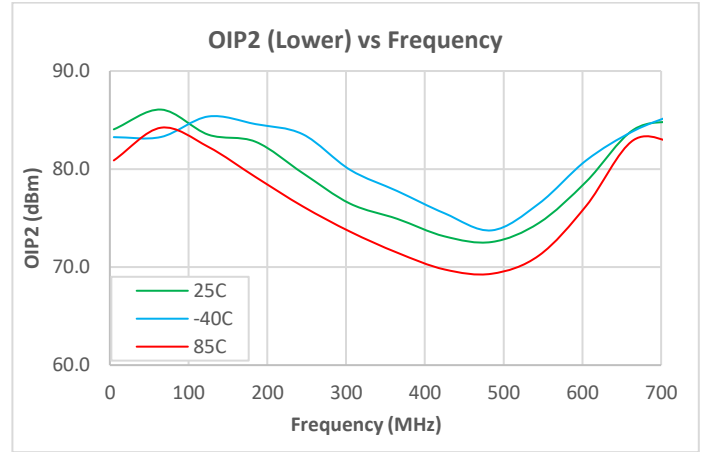
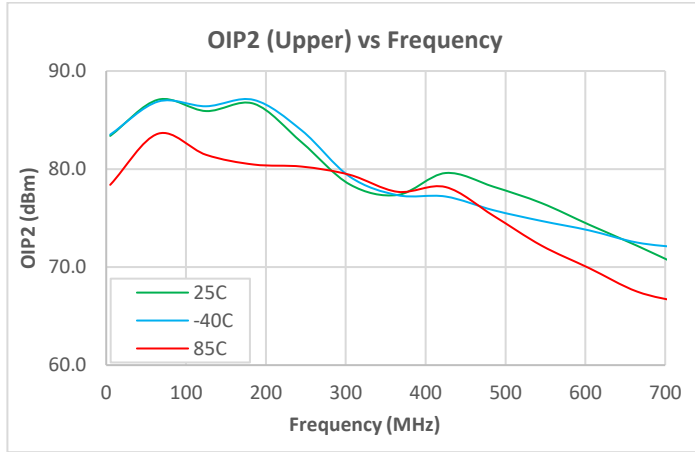
### Performance Data (5 – 700 MHz)



#### Notes:

- (1) OIP3: +5 dBm/tone, 6 MHz spacing

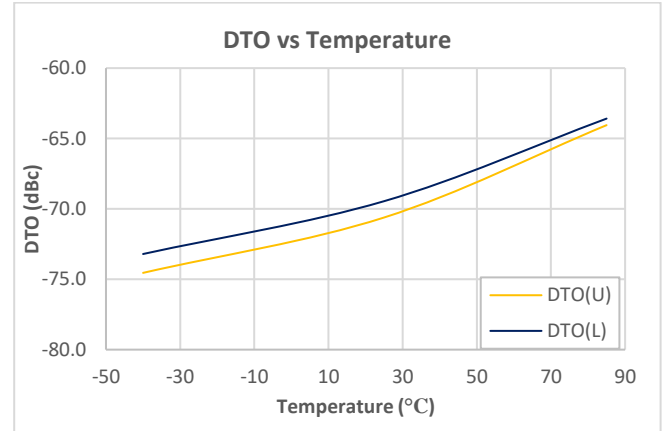
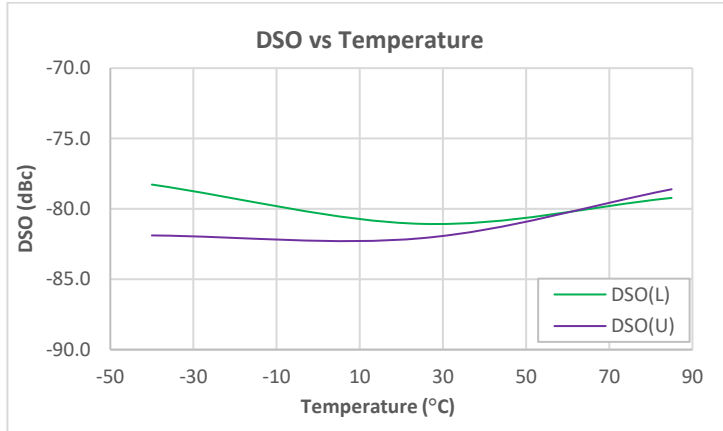
### Performance Data (5 – 700 MHz)



#### Notes:

- (1) OIP2: 3 dBm/tone, 6 MHz spacing
- (2) ACLR: Pout = 62 dBmV, 5-195 MHz OFDM w/ 9.6 MHz exclusion band.
- (3) IDD vs VDD, -10 dBm input power at 125 MHz
- (4) IDD vs Temperature, -10 dBm input power at 125 MHz, VDD = 5 V.

### Performance Data (5 – 700 MHz)

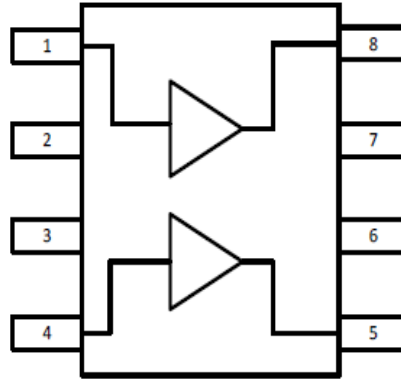


Notes:

(1) DSO/DTO: f1=13 MHz, f2=19 MHz 62 dBmV per tone

(1)

### Pin Configuration and Description

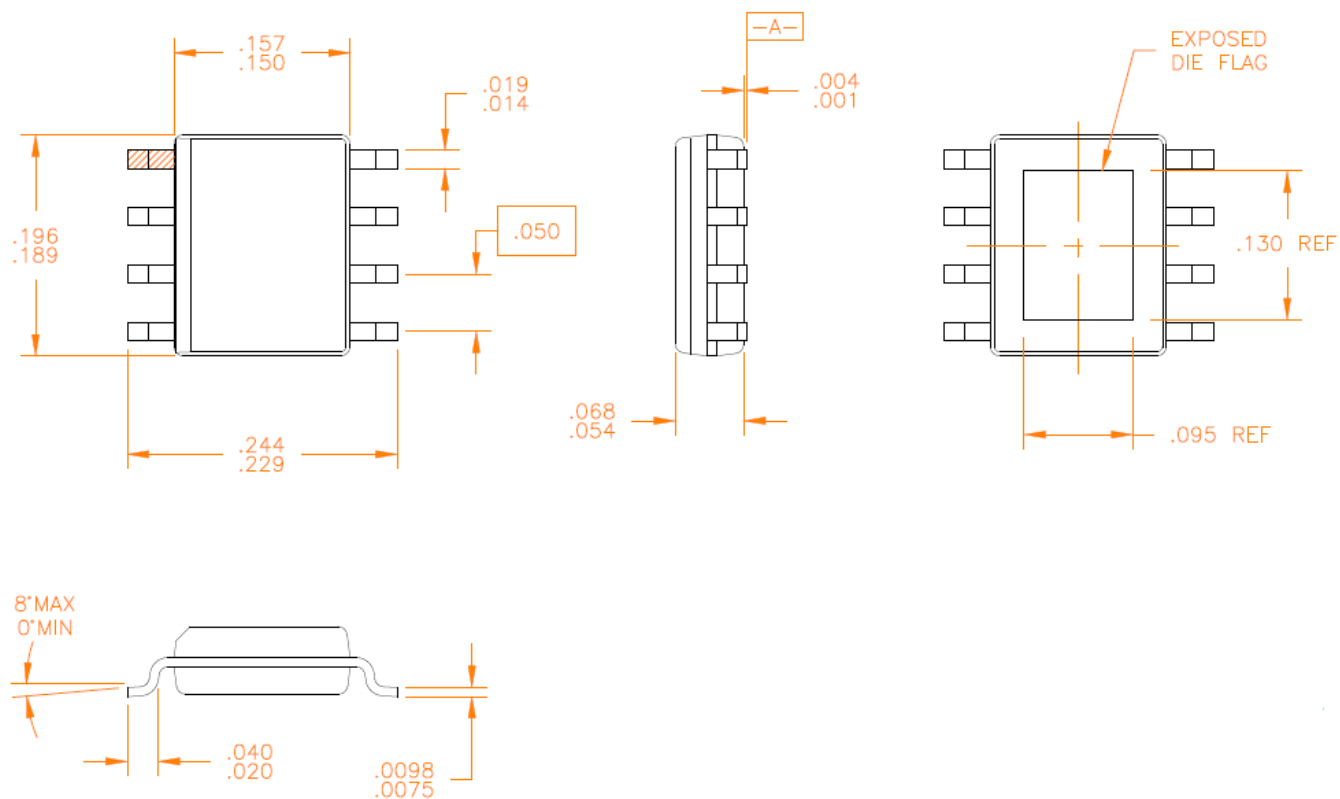


Functional Block Diagram

[Top View](#)

Pin Number	Label	Description
1	RFIN1	RF Input for plus side of amplifier
2	GND	Internally Not Connected
3	GND	Internally Not Connected
4	RFIN2	RF Input for minus side of amplifier
5	RFOUT2	RF Output for minus side of amplifier
6	NC	Not Connected
7	GND	Internally Not Connected
8	RFOUT1	RF Output for plus side of amplifier
Backside Paddle	GND	Ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint.

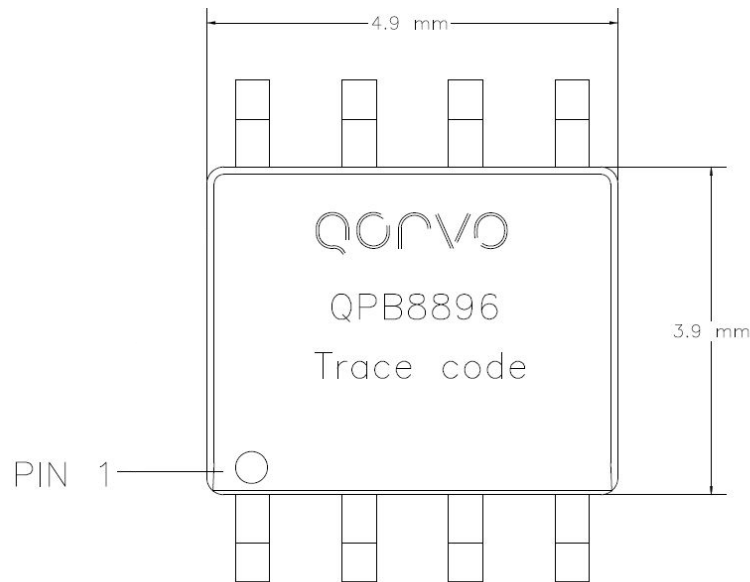
## Package Outline



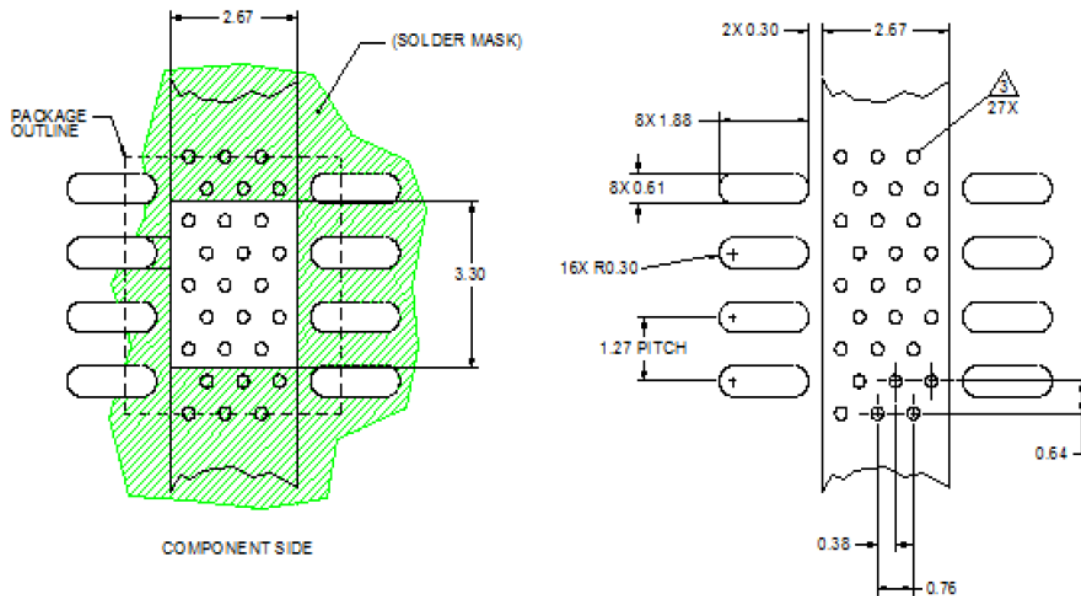
### Notes:

1. Dimensions in millimeters

### Package Marking



### Recommended Mounting Pattern



#### Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layers
3. Vias are required under the backside paddle for proper RF/DC grounding and thermal dissipation. We recommend a 0.35 mm (#80/0.135") diameter bit for drilling via holes and a final plated through diameter of 0.25 mm (0.010").
4. Ensure good backside paddle solder attach for reliable operation and best electrical performance.





# QPB8896

## 25 dB Balanced Return Path Amplifier (5 – 700 MHz)

### Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	1A (250V)	ESDA / JEDEC JS-001-2012
ESD – Charged Device Model (CDM)	C3 (1000V)	JEDEC JESD22-C101F
MSL – Moisture Sensitivity Level	MSL2	IPC/JEDEC J-STD-020



Caution!  
ESD-Sensitive Device

### Solderability

Compatible with both lead-free (260 °C max. reflow temp.) and tin/lead (245 °C max. reflow temp.) soldering processes.

Solder profiles available upon request.

Contact plating: Matte Sn

### RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- PFOS Free
- SVHC Free



### Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Tel: 1-844-890-8163

Web: [www.qorvo.com](http://www.qorvo.com)

Email: [customer.support@qorvo.com](mailto:customer.support@qorvo.com)

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